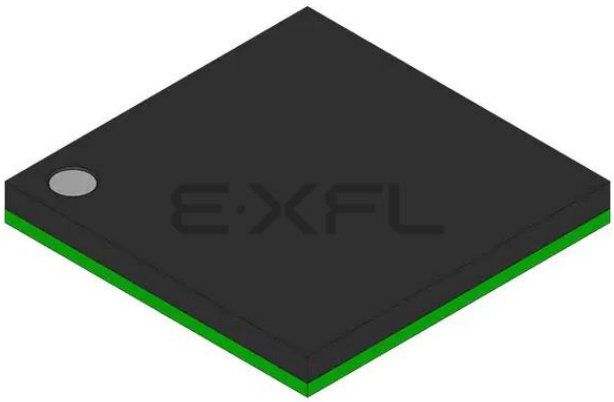


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8-Bit
Speed	8MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	86
Program Memory Size	256KB (128K x 16)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-VFBGA
Supplier Device Package	100-VFBGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/atmega2560v-8cu

Figure 1-2. CBGA-pinout ATmega640/1280/2560

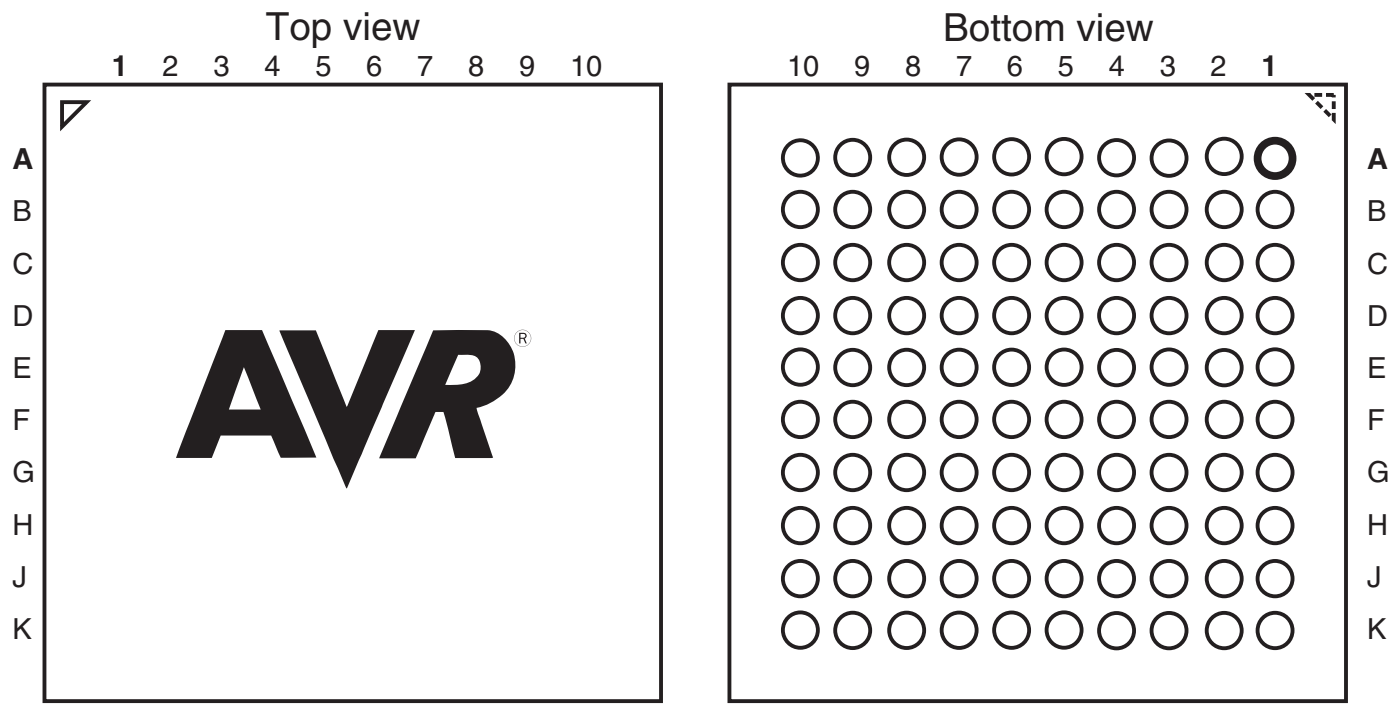
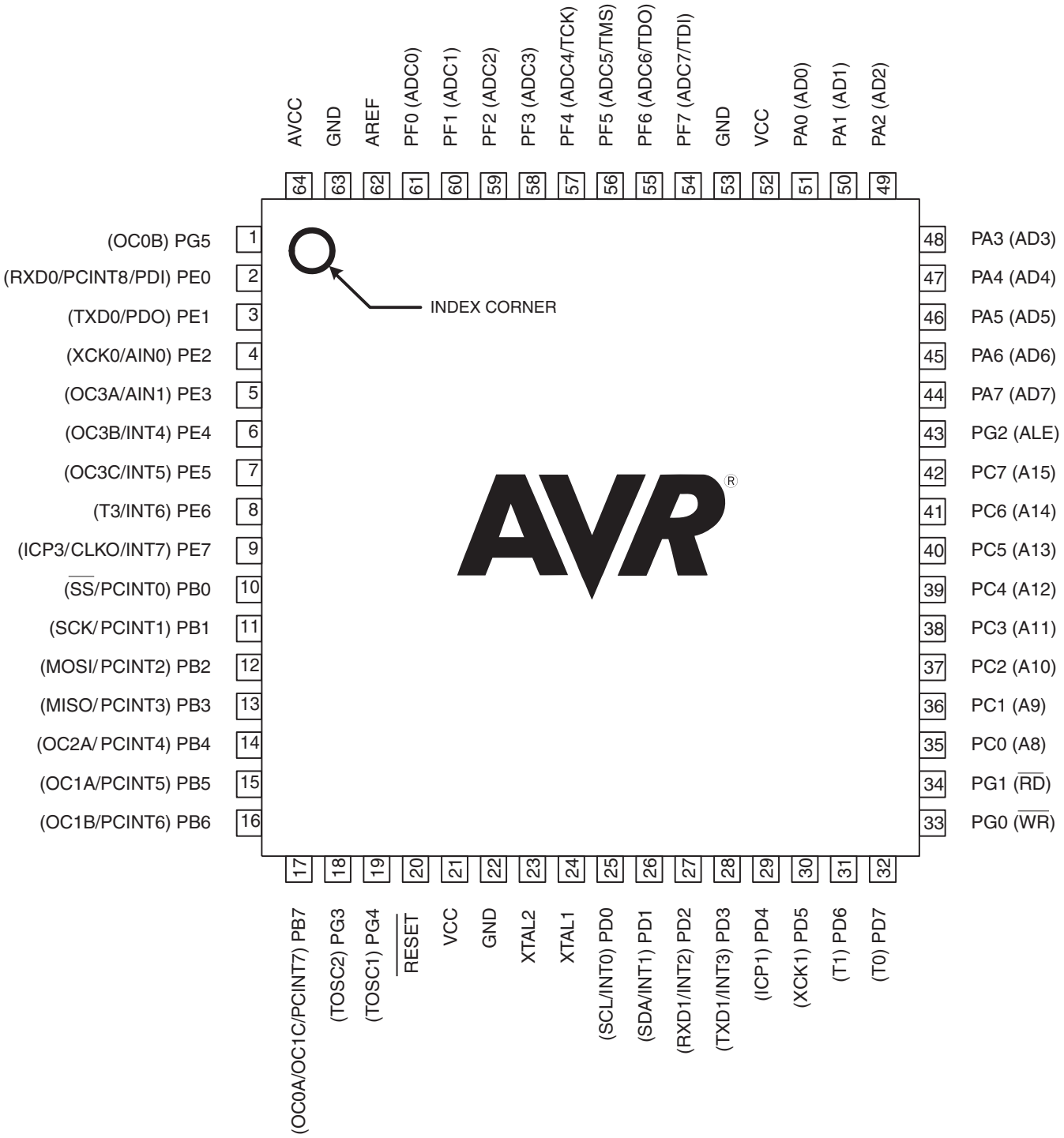


Table 1-1. CBGA-pinout ATmega640/1280/2560

	1	2	3	4	5	6	7	8	9	10
A	GND	AREF	PF0	PF2	PF5	PK0	PK3	PK6	GND	VCC
B	AVCC	PG5	PF1	PF3	PF6	PK1	PK4	PK7	PA0	PA2
C	PE2	PE0	PE1	PF4	PF7	PK2	PK5	PJ7	PA1	PA3
D	PE3	PE4	PE5	PE6	PH2	PA4	PA5	PA6	PA7	PG2
E	PE7	PH0	PH1	PH3	PH5	PJ6	PJ5	PJ4	PJ3	PJ2
F	VCC	PH4	PH6	PB0	PL4	PD1	PJ1	PJ0	PC7	GND
G	GND	PB1	PB2	PB5	PL2	PD0	PD5	PC5	PC6	VCC
H	PB3	PB4	RESET	PL1	PL3	PL7	PD4	PC4	PC3	PC2
J	PH7	PG3	PB6	PL0	XTAL2	PL6	PD3	PC1	PC0	PG1
K	PB7	PG4	VCC	GND	XTAL1	PL5	PD2	PD6	PD7	PG0

Note: The functions for each pin is the same as for the 100 pin packages shown in Figure 1-1 on page 2.

Figure 1-3. Pinout ATmega1281/2561



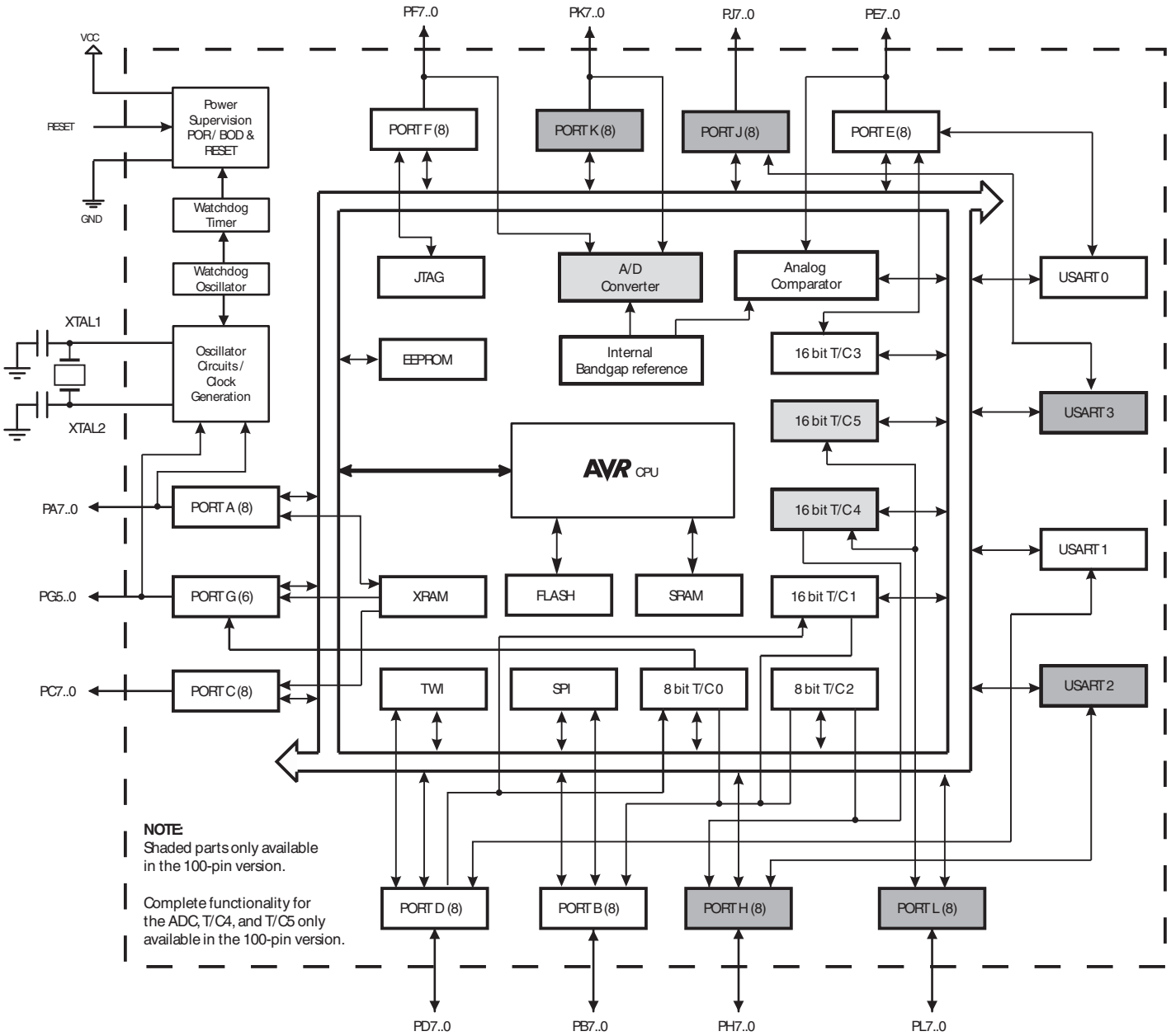
Note: The large center pad underneath the QFN/MLF package is made of metal and internally connected to GND. It should be soldered or glued to the board to ensure good mechanical stability. If the center pad is left unconnected, the package might loosen from the board.

2. Overview

The ATmega640/1280/1281/2560/2561 is a low-power CMOS 8-bit microcontroller based on the AVR enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the ATmega640/1280/1281/2560/2561 achieves throughputs approaching 1 MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

2.1 Block Diagram

Figure 2-1. Block Diagram



The Atmel® AVR® core combines a rich instruction set with 32 general purpose working registers. All the 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

The ATmega640/1280/1281/2560/2561 provides the following features: 64K/128K/256K bytes of In-System Programmable Flash with Read-While-Write capabilities, 4Kbytes EEPROM, 8Kbytes SRAM, 54/86 general purpose I/O lines, 32 general purpose working registers, Real Time Counter (RTC), six flexible Timer/Counters with compare modes and PWM, four USARTs, a byte oriented 2-wire Serial Interface, a 16-channel, 10-bit ADC with optional differential input stage with programmable gain, programmable Watchdog Timer with Internal Oscillator, an SPI serial port, IEEE® std. 1149.1 compliant JTAG test interface, also used for accessing the On-chip Debug system and programming and six software selectable power saving modes. The Idle mode stops the CPU while allowing the SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next interrupt or Hardware Reset. In Power-save mode, the asynchronous timer continues to run, allowing the user to maintain a timer base while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except Asynchronous Timer and ADC, to minimize switching noise during ADC conversions. In Standby mode, the Crystal/Resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low power consumption. In Extended Standby mode, both the main Oscillator and the Asynchronous Timer continue to run.

Atmel offers the QTouch® library for embedding capacitive touch buttons, sliders and wheels functionality into AVR microcontrollers. The patented charge-transfer signal acquisition offersrobust sensing and includes fully debounced reporting of touch keys and includes Adjacent Key Suppression® (AKS®) technology for unambiguous detection of key events. The easy-to-use QTouch Suite toolchain allows you to explore, develop and debug your own touch applications.

The device is manufactured using the Atmel high-density nonvolatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed in-system through an SPI serial interface, by a conventional nonvolatile memory programmer, or by an On-chip Boot program running on the AVR core. The boot program can use any interface to download the application program in the application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the Atmel ATmega640/1280/1281/2560/2561 is a powerful microcontroller that provides a highly flexible and cost effective solution to many embedded control applications.

The ATmega640/1280/1281/2560/2561 AVR is supported with a full suite of program and system development tools including: C compilers, macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.

2.2 Comparison Between ATmega1281/2561 and ATmega640/1280/2560

Each device in the ATmega640/1280/1281/2560/2561 family differs only in memory size and number of pins. Table 2-1 summarizes the different configurations for the six devices.

Table 2-1. Configuration Summary

Device	Flash	EEPROM	RAM	General Purpose I/O pins	16 bits resolution PWM channels	Serial USARTs	ADC Channels
ATmega640	64KB	4KB	8KB	86	12	4	16
ATmega1280	128KB	4KB	8KB	86	12	4	16
ATmega1281	128KB	4KB	8KB	54	6	2	8
ATmega2560	256KB	4KB	8KB	86	12	4	16
ATmega2561	256KB	4KB	8KB	54	6	2	8

2.3 Pin Descriptions

2.3.1 VCC

Digital supply voltage.

2.3.2 GND

Ground.

2.3.3 Port A (PA7..PA0)

Port A is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port A output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port A pins that are externally pulled low will source current if the pull-up resistors are activated. The Port A pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port A also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 75.

2.3.4 Port B (PB7..PB0)

Port B is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port B output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port B pins that are externally pulled low will source current if the pull-up resistors are activated. The Port B pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B has better driving capabilities than the other ports.

Port B also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 76.

2.3.5 Port C (PC7..PC0)

Port C is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port C output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port C pins that are externally pulled low will source current if the pull-up resistors are activated. The Port C pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port C also serves the functions of special features of the ATmega640/1280/1281/2560/2561 as listed on page 79.

2.3.12 Port K (PK7..PK0)

Port K serves as analog inputs to the A/D Converter.

Port K is a 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port K output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port K pins that are externally pulled low will source current if the pull-up resistors are activated. The Port K pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port K also serves the functions of various special features of the ATmega640/1280/2560 as listed on page 92.

2.3.13 Port L (PL7..PL0)

Port L is a 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port L output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port L pins that are externally pulled low will source current if the pull-up resistors are activated. The Port L pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port L also serves the functions of various special features of the ATmega640/1280/2560 as listed on page 94.

2.3.14 $\overline{\text{RESET}}$

Reset input. A low level on this pin for longer than the minimum pulse length will generate a reset, even if the clock is not running. The minimum pulse length is given in “System and Reset Characteristics” on page 360. Shorter pulses are not guaranteed to generate a reset.

2.3.15 XTAL1

Input to the inverting Oscillator amplifier and input to the internal clock operating circuit.

2.3.16 XTAL2

Output from the inverting Oscillator amplifier.

2.3.17 AVCC

AVCC is the supply voltage pin for Port F and the A/D Converter. It should be externally connected to V_{CC}, even if the ADC is not used. If the ADC is used, it should be connected to V_{CC} through a low-pass filter.

2.3.18 AREF

This is the analog reference pin for the A/D Converter.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
0x14 (0x34)	PORTG	-	-	PORTG5	PORTG4	PORTG3	PORTG2	PORTG1	PORTG0	page 98
0x13 (0x33)	DDRG	-	-	DDG5	DDG4	DDG3	DDG2	DDG1	DDG0	page 98
0x12 (0x32)	PING	-	-	PING5	PING4	PING3	PING2	PING1	PING0	page 98
0x11 (0x31)	PORTF	PORTF7	PORTF6	PORTF5	PORTF4	PORTF3	PORTF2	PORTF1	PORTF0	page 97
0x10 (0x30)	DDRF	DDF7	DDF6	DDF5	DDF4	DDF3	DDF2	DDF1	DDF0	page 98
0x0F (0x2F)	PINF	PINF7	PINF6	PINF5	PINF4	PINF3	PINF2	PINF1	PINF0	page 98
0x0E (0x2E)	PORTE	PORTE7	PORTE6	PORTE5	PORTE4	PORTE3	PORTE2	PORTE1	PORTE0	page 97
0x0D (0x2D)	DDRE	DDE7	DDE6	DDE5	DDE4	DDE3	DDE2	DDE1	DDE0	page 97
0x0C (0x2C)	PINE	PINE7	PINE6	PINE5	PINE4	PINE3	PINE2	PINE1	PINE0	page 98
0x0B (0x2B)	PORTD	PORTD7	PORTD6	PORTD5	PORTD4	PORTD3	PORTD2	PORTD1	PORTD0	page 97
0x0A (0x2A)	DDRD	DDD7	DDD6	DDD5	DDD4	DDD3	DDD2	DDD1	DDD0	page 97
0x09 (0x29)	PIND	PIND7	PIND6	PIND5	PIND4	PIND3	PIND2	PIND1	PIND0	page 97
0x08 (0x28)	PORTC	PORTC7	PORTC6	PORTC5	PORTC4	PORTC3	PORTC2	PORTC1	PORTC0	page 97
0x07 (0x27)	DDRC	DDC7	DDC6	DDC5	DDC4	DDC3	DDC2	DDC1	DDC0	page 97
0x06 (0x26)	PINC	PINC7	PINC6	PINC5	PINC4	PINC3	PINC2	PINC1	PINC0	page 97
0x05 (0x25)	PORTB	PORTB7	PORTB6	PORTB5	PORTB4	PORTB3	PORTB2	PORTB1	PORTB0	page 96
0x04 (0x24)	DDRB	DDB7	DDB6	DDB5	DDB4	DDB3	DDB2	DDB1	DDB0	page 96
0x03 (0x23)	PINB	PINB7	PINB6	PINB5	PINB4	PINB3	PINB2	PINB1	PINB0	page 96
0x02 (0x22)	PORTA	PORTA7	PORTA6	PORTA5	PORTA4	PORTA3	PORTA2	PORTA1	PORTA0	page 96
0x01 (0x21)	DDRA	DDA7	DDA6	DDA5	DDA4	DDA3	DDA2	DDA1	DDA0	page 96
0x00 (0x20)	PINA	PINA7	PINA6	PINA5	PINA4	PINA3	PINA2	PINA1	PINA0	page 96

Notes:
1. For compatibility with future devices, reserved bits should be written to zero if accessed. Reserved I/O memory addresses should never be written.
2. I/O registers within the address range $00 - $1F are directly bit-accessible using the SBI and CBI instructions. In these registers, the value of single bits can be checked by using the SBIS and SBIC instructions.
3. Some of the status flags are cleared by writing a logical one to them. Note that the CBI and SBI instructions will operate on all bits in the I/O register, writing a one back into any flag read as set, thus clearing the flag. The CBI and SBI instructions work with registers 0x00 to 0x1F only.
4. When using the I/O specific commands IN and OUT, the I/O addresses $00 - $3F must be used. When addressing I/O registers as data space using LD and ST instructions, $20 must be added to these addresses. The ATmega640/1280/1281/2560/2561 is a complex microcontroller with more peripheral units than can be supported within the 64 location reserved in Opcode for the IN and OUT instructions. For the Extended I/O space from $60 - $1FF in SRAM, only the ST/STS/STD and LD/LDS/LDD instructions can be used.

Mnemonics	Operands	Description	Operation	Flags	#Clocks
OUT	P, Rr	Out Port	P ← Rr	None	1
PUSH	Rr	Push Register on Stack	STACK ← Rr	None	2
POP	Rd	Pop Register from Stack	Rd ← STACK	None	2
MCU CONTROL INSTRUCTIONS					
NOP		No Operation		None	1
SLEEP		Sleep	(see specific descr. for Sleep function)	None	1
WDR		Watchdog Reset	(see specific descr. for WDR/timer)	None	1
BREAK		Break	For On-chip Debug Only	None	N/A

Note: EICALL and EIJMP do not exist in ATmega640/1280/1281.
ELPM does not exist in ATmega640.

9. Ordering Information

9.1 ATmega640

Speed [MHz](2)	Power Supply	Ordering Code	Package(1)(3)	Operation Range
8	1.8 - 5.5V	ATmega640V-8AU ATmega640V-8AUR(4) ATmega640V-8CU ATmega640V-8CUR(4)	100A 100A 100C1 100C1	Industrial (-40°C to 85°C)
16	2.7 - 5.5V	ATmega640-16AU ATmega640-16AUR(4) ATmega640-16CU ATmega640-16CUR(4)	100A 100A 100C1 100C1	

Notes:
1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See “Speed Grades” on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
100A	100-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
100C1	100-ball, Chip Ball Grid Array (CBGA)

9.2 ATmega1280

Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8V - 5.5V	ATmega1280V-8AU ATmega1280V-8AUR[4] ATmega1280V-8CU ATmega1280V-8CUR[4]	100A 100A 100C1 100C1	Industrial (-40°C to 85°C)
16	2.7V - 5.5V	ATmega1280-16AU ATmega1280-16AUR[4] ATmega1280-16CU ATmega1280-16CUR[4]	100A 100A 100C1 100C1	

Notes:
1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See “Speed Grades” on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
100A	100-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
100C1	100-ball, Chip Ball Grid Array (CBGA)

9.3 ATmega1281

Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8 - 5.5V	ATmega1281V-8AU ATmega1281V-8AUR[4] ATmega1281V-8MU ATmega1281V-8MUR[4]	64A 64A 64M2 64M2	Industrial (-40°C to 85°C)
16	2.7 - 5.5V	ATmega1281-16AU ATmega1281-16AUR[4] ATmega1281-16MU ATmega1281-16MUR[4]	64A 64A 64M2 64M2	

Notes:
1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See "Speed Grades" on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
64A	64-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
64M2	64-pad, 9mm × 9mm × 1.0mm Body, Quad Flat No-lead/Micro Lead Frame Package (QFN/MLF)

9.4 ATmega2560

Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8V - 5.5V	ATmega2560V-8AU ATmega2560V-8AUR[4] ATmega2560V-8CU ATmega2560V-8CUR[4]	100A 100A 100C1 100C1	Industrial (-40°C to 85°C)
16	4.5V - 5.5V	ATmega2560-16AU ATmega2560-16AUR[4] ATmega2560-16CU ATmega2560-16CUR[4]	100A 100A 100C1 100C1	

Notes:
1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See “Speed Grades” on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
100A	100-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
100C1	100-ball, Chip Ball Grid Array (CBGA)

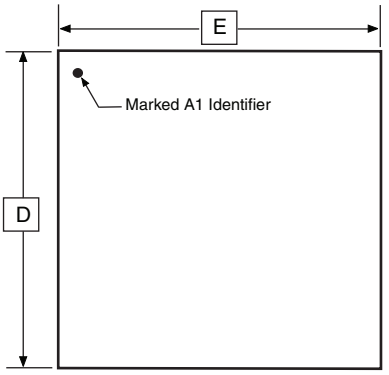
9.5 ATmega2561

Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8V - 5.5V	ATmega2561V-8AU ATmega2561V-8AUR[4] ATmega2561V-8MU ATmega2561V-8MUR[4]	64A 64A 64M2 64M2	Industrial (-40°C to 85°C)
16	4.5V - 5.5V	ATmega2561-16AU ATmega2561-16AUR[4] ATmega2561-16MU ATmega2561-16MUR[4]	64A 64A 64M2 64M2	

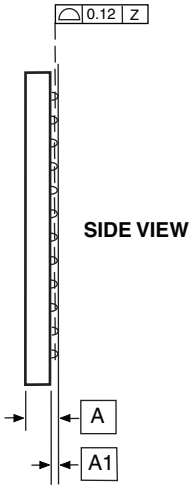
Notes:
1. This device can also be supplied in wafer form.Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See “Speed Grades” on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

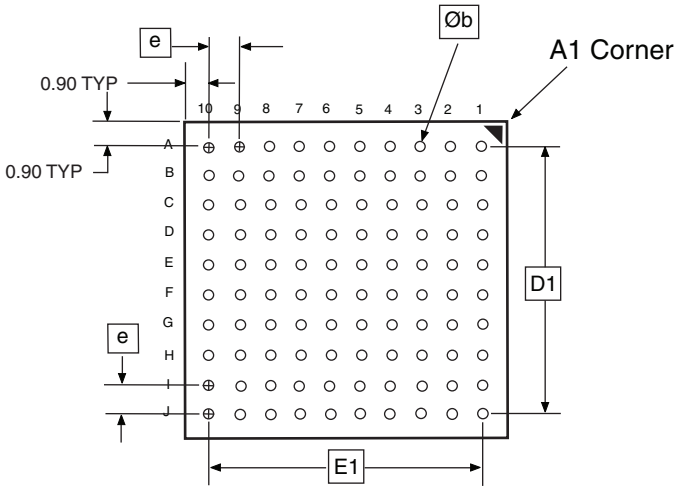
Package Type	
64A	64-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
64M2	64-pad, 9mm × 9mm × 1.0mm Body, Quad Flat No-lead/Micro Lead Frame Package (QFN/MLF)

10.2 100C1



TOP VIEW





BOTTOM VIEW

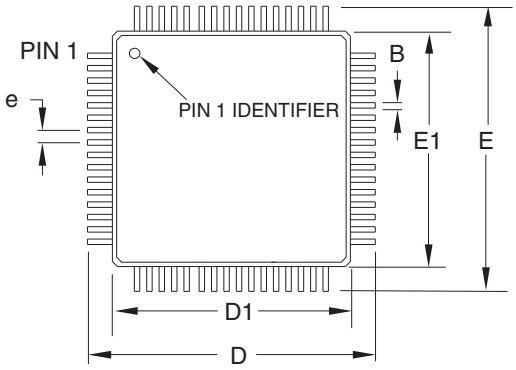
COMMON DIMENSIONS
(Unit of Measure = mm)

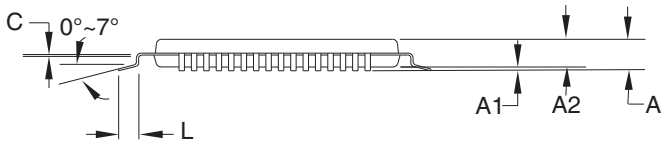
SYMBOL	MIN	NOM	MAX	NOTE
A	1.10	–	1.20	
A1	0.30	0.35	0.40	
D	8.90	9.00	9.10	
E	8.90	9.00	9.10	
D1	7.10	7.20	7.30	
E1	7.10	7.20	7.30	
Øb	0.35	0.40	0.45	
e	0.80 TYP			

5/25/06

	TITLE	DRAWING NO.	REV.
Atmel 2325 Orchard Parkway San Jose, CA 95131	**100C1**, 100-ball, 9 x 9 x 1.2 mm Body, Ball Pitch 0.80 mm Chip Array BGA Package (CBGA)	100C1	A

10.3 64A





COMMON DIMENSIONS
(Unit of measure = mm)

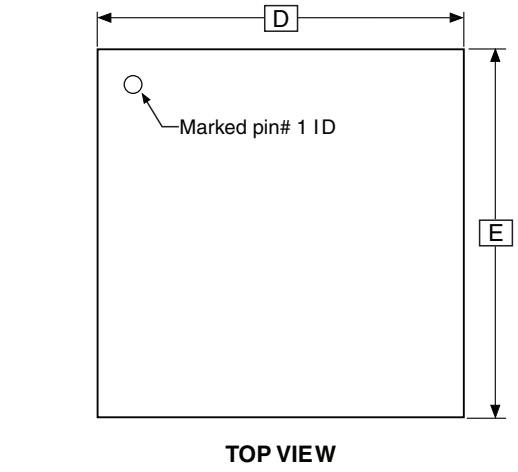
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	15.75	16.00	16.25	
D1	13.90	14.00	14.10	Note 2
E	15.75	16.00	16.25	
E1	13.90	14.00	14.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

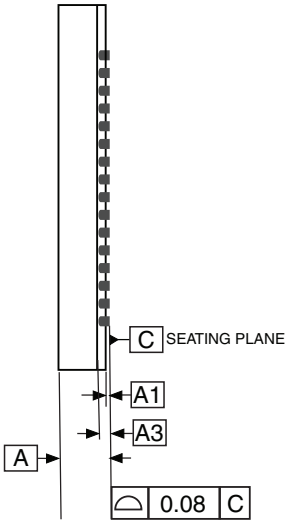
Notes:
1. This package conforms to JEDEC reference MS-026, Variation AEB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

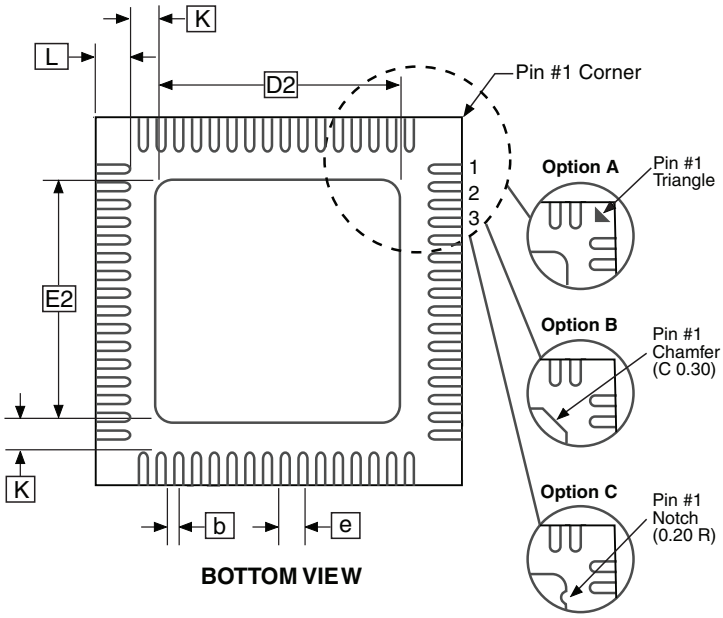
2010-10-20

	TITLE	DRAWING NO.	REV.
Atmel 2325 Orchard Parkway San Jose, CA 95131	**64A,** 64-lead, 14 x 14mm Body Size, 1.0mm Body Thickness, 0.8mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	64A	C

10.4 64M2







COMMON DIMENSIONS
(Unit of measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	0.90	1.00	
A1	–	0.02	0.05	
A3		0.20 REF		
b	0.18	0.25	0.30	
D	8.90	9.00	9.10	
D2	7.50	7.65	7.80	
E	8.90	9.00	9.10	
E2	7.50	7.65	7.80	
e		0.50 BSC		
L	0.35	0.40	0.45	
K	0.20	0.27	0.40	

Notes: 1. JEDEC Standard MO-220, (SAW Singulation) fig . 1, VMMD.
2. Dimension and tolerance conform to ASMEY14.5M-1994.

2014-02-12

	TITLE	DRAWING NO.	REV.
Atmel 2325 Orchard Parkway San Jose, CA 95131	**64M2**, 64-pad, 9 x 9 x 1.0mm Bod y, Lead Pitch 0.50mm , 7.65mm Exposed Pad, Micro Lead Frame Package (MLF)	64M2	E

11.10 ATmega2560 rev. C

- **High current consumption in sleep mode**

1. **High current consumption in sleep mode**
   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround
   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.11 ATmega2560 rev. B

Not sampled.

11.12 ATmega2560 rev. A

- **Non-Read-While-Write area of flash not functional**
- **Part does not work under 2.4 volts**
- **Incorrect ADC reading in differential mode**
- **Internal ADC reference has too low value**
- **IN/OUT instructions may be executed twice when Stack is in external RAM**
- **EEPROM read from application code does not work in Lock Bit Mode 3**

1. **Non-Read-While-Write area of flash not functional**
   The Non-Read-While-Write area of the flash is not working as expected. The problem is related to the speed of the part when reading the flash of this area.

   Problem Fix/Workaround
   - Only use the first 248K of the flash.

   - If boot functionality is needed, run the code in the Non-Read-While-Write area at maximum 1/4th of the maximum frequency of the device at any given voltage. This is done by writing the CLKPR register before entering the boot section of the code.

2. **Part does not work under 2.4 volts**
   The part does not execute code correctly below 2.4 volts.

   Problem Fix/Workaround
   Do not use the part at voltages below 2.4 volts.

3. **Incorrect ADC reading in differential mode**
   The ADC has high noise in differential mode. It can give up to 7 LSB error.

   Problem Fix/Workaround
   Use only the 7 MSB of the result when using the ADC in differential mode.

4. **Internal ADC reference has too low value**
   The internal ADC reference has a value lower than specified.

   Problem Fix/Workaround
   - Use AVCC or external reference.

   - The actual value of the reference can be measured by applying a known voltage to the ADC when using the internal reference. The result when doing later conversions can then be calibrated.

5. **IN/OUT instructions may be executed twice when Stack is in external RAM**
   If either an IN or an OUT instruction is executed directly before an interrupt occurs and the stack pointer is located in external ram, the instruction will be executed twice. In some cases this will cause a problem, for example:

   - If reading SREG it will appear that the I-flag is cleared.

   - If writing to the PIN registers, the port will toggle twice.

   - If reading registers with interrupt flags, the flags will appear to be cleared.

   Problem Fix/Workaround
   There are two application workarounds, where selecting one of them, will be omitting the issue:

   - Replace IN and OUT with LD/LDS/LDD and ST/STS/STD instructions.

   - Use internal RAM for stack pointer.

6. **EEPROM read from application code does not work in Lock Bit Mode 3**
   When the Memory Lock Bits LB2 and LB1 are programmed to mode 3, EEPROM read does not work from the application code.

   Problem Fix/Workaround
   Do not set Lock Bit Protection Mode 3 when the application code needs to read from EEPROM.

11.13 ATmega2561 rev. F

- **ADC differential input amplification by 46dB (200x) not functional**

1. **ADC differential input amplification by 46dB (200x) not functional**
   Problem Fix/Workaround
   None.

11.14 ATmega2561 rev. E

No known errata.

11.15 ATmega2561 rev. D

Not sampled.

11.16 ATmega2561 rev. C

- **High current consumption in sleep mode.**

1. **High current consumption in sleep mode**
   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround
   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.17 ATmega2561 rev. B

Not sampled.

- Use internal RAM for stack pointer.

6. **EEPROM read from application code does not work in Lock Bit Mode 3**

   When the Memory Lock Bits LB2 and LB1 are programmed to mode 3, EEPROM read does not work from the application code.

   Problem Fix/Workaround

   Do not set Lock Bit Protection Mode 3 when the application code needs to read from EEPROM.

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